



Product Change Notification / ALAN-20BLUP482

Date:

23-Sep-2021

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4847 Initial Notice: Qualification of ATP7 as an additional assembly site for selected Atmel ATSAM51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

Affected CPNs:

[ALAN-20BLUP482_Affected_CPN_09232021.pdf](#)
[ALAN-20BLUP482_Affected_CPN_09232021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type:
Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ATP7 as an additional assembly site for ATSAM51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

Pre and Post Change Summary:

| | Pre Change | Post Change |
|--|------------|-------------|
| | | |

| | | | | |
|-------------------------------|------------------------------------|----------------|----------------|---|
| Assembly location | | ASE Inc. (ASE) | ASE Inc. (ASE) | Amkor Technology Philippines (P3/P4), INC. (ATP7) |
| Bond wire material | | CuPdAu | CuPdAu | CuPdAu |
| Die attach material | | EN-4900F | EN-4900F | CRM1085A |
| Mold compound material | | G631H | G631H | G631BQF |
| Lead-frame | Material | C194 | C194 | C194 |
| | Paddle Size | 193 X 193 | 193 X 193 | 197X197 |
| | See pre and post change comparison | | | |

Impacts to Data Sheet: None.

Change Impact:None.

Reason for Change:

To improve manufacturability and on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:February 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

| | September 2021 | | | | | | February 2022 | | | | |
|--------------------------|----------------|----|----|----|----|----|---------------|---|---|---|---|
| Workweek | 36 | 37 | 38 | 39 | 40 | -> | 5 | 6 | 7 | 8 | 9 |
| Initial PCN Issue Date | | | | X | | | | | | | |
| Qual Report Availability | | | | | | | | | X | | |
| Final PCN Issue | | | | | | | | | X | | |

CCB 4847
Pre and Post Change Summary
PCN# ALAN-20BLUP482



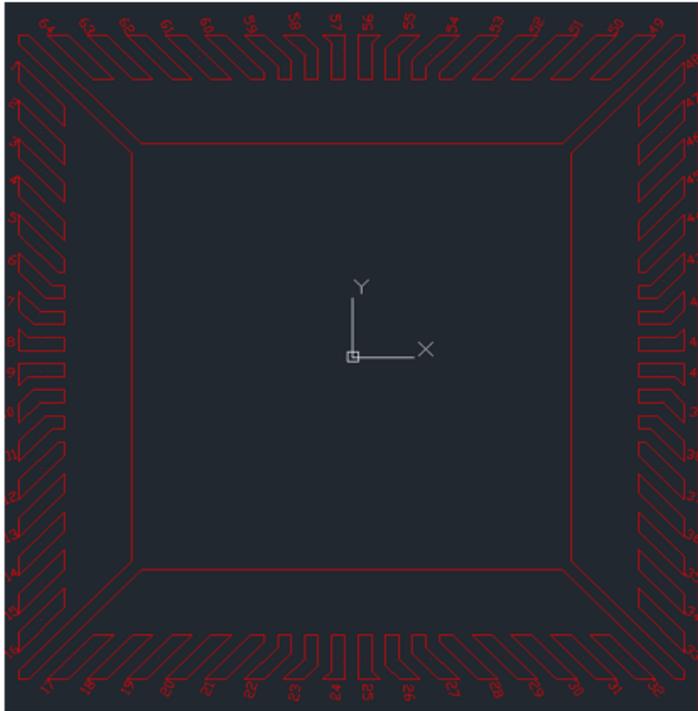
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

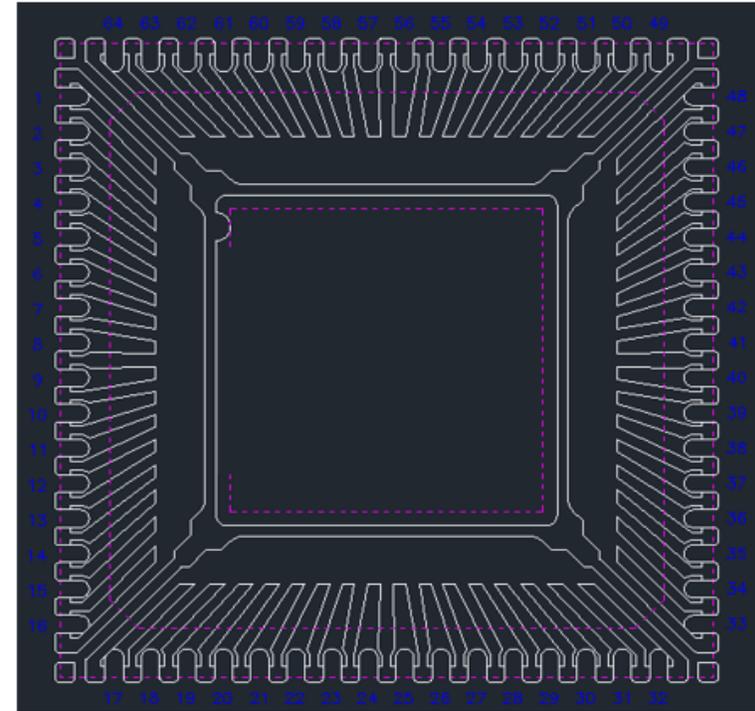
Pre and Post Change Summary

ASE Inc. (ASE)



| | |
|-------------|-----------|
| Material | C194 |
| Paddle size | 193 X 193 |

Amkor Technology Philippines (P3/P4), INC. (ATP7)



| | |
|-------------|---------|
| Material | C194 |
| Paddle size | 197X197 |



QUALIFICATION PLAN SUMMARY

PCN#: ALAN-20BLUP482

**Date:
September 16, 2021**

Qualification of ATP7 as an additional assembly site for selected Atmel ATSAMD51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

Purpose: Qualification of ATP7 as an additional assembly site for selected Atmel ATSAM51Jxx and ATSAME5xx device families available in 64L VQFN (9x9x1.0mm) package.

| | | |
|-------------------|--|---------------------|
| <u>Misc.</u> | Assembly site | ATP7 |
| | BD Number | TBD |
| | MP Code (MPC) | 651067TMBC05 |
| | Part Number (CPN) | ATSAMD51J20A-MU |
| | MSL information | MSL-3 @260C |
| | Assembly Shipping Media (T/R, Tube/Tray) | Kostat KS-870274 |
| | Base Quantity Multiple (BQM) | Tray -260 |
| | Reliability Site | MPHIL |
| | CCB No. | 4847 |
| <u>Lead-Frame</u> | Paddle size | 197X197 (5X5mm) |
| | Material | C194 |
| | DAP Surface Prep | Double Ring Plating |
| | Treatment | Roughened |
| | Process | Etched |
| | Lead-lock (With Locking Holes) | No |
| | Part Number | 101419822 |
| | Lead Plating | Matte Sn |
| | Strip Size | 250 X 70mm |
| <u>Bond Wire</u> | Material | CuPdAu |
| <u>Die Attach</u> | Part Number | CRM1085A |
| | Conductive | Yes |
| <u>MC</u> | Part Number | G631BQF |

| Test Name | Conditions | Sample Size | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty | Est. Dur. Days | ATE Test Site | REL Test Site | Pkg. Type | Special Instructions |
|--------------------------------|--|---|--|-------------|-------------|---------------------|----------------|---------------|---------------|-----------|---|
| Standard Pb-free Solderability | J-STD-002D; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages. | 22 | 5 | 1 | 27 | > 95% lead coverage | 5 | MPHIL | MPHIL | 64L VQFN | Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes. |
| Wire Bond Pull - WBP | Mil. Std. 883-2011 | 5 | 0 | 1 | 5 | 0 | 5 | MPHIL | MPHIL | 64L VQFN | 30 bonds from a min. 5 devices. |
| Wire Bond Shear - WBS | CDF-AEC-Q100-001 | 5 | 0 | 1 | 5 | 0 | 5 | MPHIL | MPHIL | 64L VQFN | 30 bonds from a min. 5 devices. |
| Physical Dimensions | Measure per JESD22 B100 and B108 | 10 | 0 | 3 | 30 | 0 | 5 | MPHIL | MPHIL | 64L VQFN | |
| External Visual | Mil. Std. 883-2009/2010 | All devices prior to submission for qualification testing | 0 | 3 | ALL | 0 | 5 | MPHIL | MPHIL | 64L VQFN | |

| Test Name | Conditions | Sample Size | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty | Est. Dur. Days | ATE Test Site | REL Test Site | Pkg. Type | Special Instructions |
|---|--|-------------|--|-------------|-------------|-----------------|----------------|---------------|---------------|-----------|---|
| Preconditioning - Required for surface mount devices | +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at room temp 25°C. | 231 | 15 | 3 | 738 | 0 | 15 | MPHIL | MPHIL | 64L VQFN | Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test. |
| HAST | +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at room temp 25° | 77 | 5 | 3 | 246 | 0 | 10 | MPHIL | MPHIL | 64L VQFN | Spares should be properly identified. Use the parts which have gone through Pre-conditioning. |
| UHAST | +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at room temp 25°C. Requires 2X Rel stress Testing | 77 | 5 | 3 | 246 | 0 | 10 | MPHIL | MPHIL | 64L VQFN | Spares should be properly identified. Use the parts which have gone through Pre-conditioning. |

| Test Name | Conditions | Sample Size | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty | Est. Dur. Days | ATE Test Site | REL Test Site | Pkg. Type | Special Instructions |
|------------|--|-------------|--|-------------|-------------|-----------------|----------------|---------------|---------------|-----------|---|
| Temp Cycle | <p>-65°C to +150°C for 500 cycles.</p> <p>Electrical test pre and post stress at room; 3gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.</p> <p>Requires 2X Rel stress Testing</p> | 77 | 5 | 3 | 246 | 0 | 15 | MPHIL | MPHIL | 64L VQFN | Spares should be properly identified. Use the parts which have gone through Pre-conditioning. |

Affected Catalog Part Numbers (CPN)

ATSAME51J19A-MU
ATSAME51J18A-MU
ATSAMD51J18A-MU
ATSAMD51J19A-MU
ATSAMD51J20A-MU
ATSAME53J18A-MU
ATSAME53J19A-MU
ATSAME53J20A-MU
ATSAME51J20A-MU
ATSAMD51J18A-MU-EFP
ATSAMD51J19A-MU-EFP
ATSAMD51J20A-MU-EFP
ATSAME51J18A-MU-EFP
ATSAME51J19A-MU-EFP
ATSAME51J20A-MU-EFP
ATSAME53J18A-MU-EFP
ATSAME53J19A-MU-EFP
ATSAME53J20A-MU-EFP
ATSAMD51J19A-MUN01
ATSAME53J18A-MUN02
ATSAME51J19A-MUT
ATSAME51J18A-MUT
ATSAMD51J18A-MUT
ATSAMD51J19A-MUT
ATSAMD51J20A-MUT
ATSAME53J18A-MUT
ATSAME53J19A-MUT
ATSAME53J20A-MUT
ATSAME51J20A-MUT
ATSAMD51J18A-MUT-EFP
ATSAMD51J19A-MUT-EFP
ATSAMD51J20A-MUT-EFP
ATSAME51J18A-MUT-EFP
ATSAME51J19A-MUT-EFP
ATSAME51J20A-MUT-EFP
ATSAME53J18A-MUT-EFP
ATSAME53J19A-MUT-EFP
ATSAME53J20A-MUT-EFP
ATSAMD51J19A-MUTN01